

Ball / Land Grid Array Sockets

Quick Lock Type



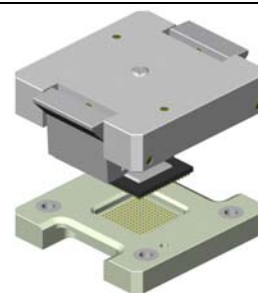
E-tec is now the leading BGA socket manufacturer.

EP patents 0829188, 0897655 US patents 6190181, 6249440 Patented in other countries.

Quick lock sockets are available for any chip size and grid pattern. They are available in SMT, thru-hole and solderless compression type versions. The SMT socket is simply placed and reflowed onto the PCB in the same way as the chip and it only requires a small amount of additional board space. A lever is added to the Quick lock retention cover if the pincount exceeds 81 pins which allows the required pressdown forces to be applied easily.

We aim to solve your requirements - many different terminals and configurations are available.

Your custom sets our standards!



Please note, we will always request the chip data to ensure we offer a compatible socket.

SMT style	Soldertail style	Solderless Compression style
<p>PCB Pad Layout</p> <p>Pitch</p> <p>solder pad</p> <p>Ø 0,60mm/.024" if pitch 1,27mm Ø 0,50mm/.020" if pitch 1,00mm Ø 0,40mm/.016" if pitch 0,80mm Ø 0,35mm/.014" if pitch 0,75mm Ø 0,35mm/.014" if pitch 0,65mm Ø 0,30mm/.012" if pitch 0,50mm</p>	<p>PCB Hole Layout</p> <p>Pitch</p> <p>solder hole</p> <p>Soldertail dimension: Ø 0,42mm/.016" if pitch 1,27mm Ø 0,29mm/.011" if pitch 1,00mm Ø 0,29mm/.011" if pitch 0,80mm Ø 0,27mm/.010" if pitch 0,75mm Ø 0,27mm/.010" if pitch 0,65mm Ø 0,27mm/.010" if pitch 0,50mm Ø 0,17mm/.007" if pitch 0,40mm</p> <p>PCB solder hole: Ø 0,60mm/.024" if pitch 1,27mm Ø 0,50mm/.020" if pitch 1,00mm Ø 0,40mm/.016" if pitch 0,80mm Ø 0,35mm/.014" if pitch 0,75mm Ø 0,35mm/.014" if pitch 0,65mm Ø 0,35mm/.014" if pitch 0,50mm Ø 0,25mm/.010" if pitch 0,40mm</p>	<p>Retention Cover</p> <p>BGA Chip</p> <p>BGA socket body</p> <p>PCB</p> <p>Assembly Board</p> <p>mounting screw</p> <p>Pitch</p> <p>Solder Pad</p> <p>You may request any specific socket dimension from info@e-tec.com</p> <p>gold plated pads Ø 0,70mm/.027" if pitch 1,27mm gold plated pads Ø 0,60mm/.024" if pitch 1,00mm gold plated pads Ø 0,50mm/.020" if pitch 0,80mm gold plated pads Ø 0,45mm/.018" if pitch 0,75mm gold plated pads Ø 0,40mm/.016" if pitch 0,65mm gold plated pads Ø 0,35mm/.012" if pitch 0,50mm gold plated pads Ø 0,25mm/.010" if pitch 0,40mm</p> <p>Recommendation: E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!</p>

Important Note:
 Please check the ball diameters & heights of your chip prior to ordering the standard E-tec BGA (BPQ, BCQ) sockets. Any deviation has to be communicated to E-tec in order to check compatibility with the standard socket design and if necessary to obtain a special order code adapted to your chip dimensions. The standard solderball diameters & heights are the following:

Pitch	ball diameters min/max	ball height min/max
0.50mm	0.25mm / 0.35mm	0.15mm / 0.30mm
0.65mm	0.25mm / 0.45mm	0.15mm / 0.30mm
0.75mm	0.25mm / 0.45mm	0.15mm / 0.40mm
0.80mm	0.40mm / 0.55mm	0.25mm / 0.45mm
1.00mm	0.50mm / 0.70mm	0.30mm / 0.50mm

1.27mm & 1.50mm

a) plastic chips (BPQ)	0.60mm / 1.00mm	0.50mm / 0.70mm
b) ceramic chips (BCQ)	0.60mm / 1.00mm	0.80mm / 1.00mm

If the minimum ball diameter of a given chip falls below the above indications, then a BUQ socket will generally be proposed.

Specifications

Mechanical data	
Contact life	10.000 cycles min.
Retention System life	10.000 cycles min.
Solderability	as per IEC 60068-2-58
Individual contact force	40 grams max.
Material	
Insulator (RoHS compliant)	High temp plastic or epoxy FR4
Terminal (RoHS compliant)	Brass
Contact (RoHS compliant)	BeCu
Electrical data	
Contact resistance	< 100 mΩ
Current rating	500 mA max.
Insulation resistance at 500V DC	100 MΩ if 0.50 to 0.80mm pitch 500 MΩ 1.00mm pitch upwards
Breakdown voltage at 60 Hz	500V min.
Capacitance	< 1 pF
Inductance	< 2 nH
Operating temperature	-55°C to +125°C ; 260°C for 60 sec.
Recommendation:	
Solder paste	Please use a solder paste w/o any silver!
Solder profile	Please refer to our website www.e-tec.com

How to order

X X Q x x x x - x x x x - x x X X x x L ← optional for locating pegs

<p>Device Type</p> <p>B = Ball Grid</p> <p>L = Land Grid</p> <p>C = Column Grid</p>	<p>Device Material</p> <p>C = std. socket for ceramic device</p> <p>P = std. socket for plastic device</p> <p>U = socket adapted to small diameter solderballs</p>	<p>Pitch</p> <p>04 = 0,40mm 10 = 1,00mm</p> <p>05 = 0,50mm 12 = 1,27mm</p> <p>06 = 0,65mm 15 = 1,50mm</p> <p>07 = 0,75mm</p> <p>08 = 0,80mm</p> <p>Others on request</p>	<p>Grid Code Config Code</p> <p>will be given by the factory after receipt of the chip datasheet</p> <p>Chips with dimensions over 36x36mm: please contact E-tec for availability first.</p>	<p>Plating</p> <p>95 = tin/gold (tin leadfree)</p> <p>55 = gold only for solderless Compression Type</p>
<p>Nbr of contacts</p> <p>depends on ballcount of chip</p>	<p>Contact Type</p> <p>30 = standard SMT.... („A“ = 1,20mm if 1,27mm pitch; 0,80mm if 1,00mm pitch, 0,60 if 0,80mm pitch; 0,40mm if <0,80mm pitch)</p> <p>29 = raised SMT.. („A“ = 5,00mm if 1,27mm pitch; 3,20mm if 1,00mm pitch; 2,80mm if 0,80mm pitch, 2,30mm if <0,80mm pitch)</p> <p>28 = special raised SMT - only for 1.00 & 0.80mm pitch..... („A“ = 4,50mm)</p> <p>70 = standard solder tail..... („A“ = 3,30 if 1.27mm pitch, 2,80 if 1.00mm or 0.80mm pitch, 2,30mm if <0,80mm pitch)</p> <p>90 = solderless Compression Type</p>			